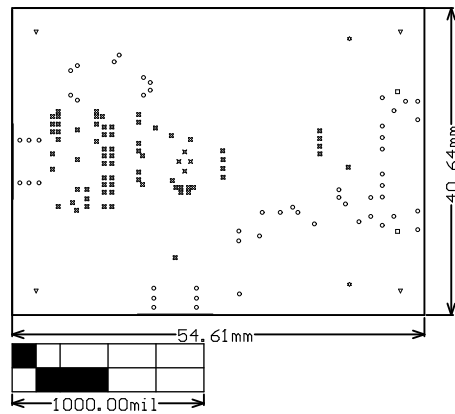


NOTE : 1. VIAS ON PAD TO BE FILLED WITH CONDUCTIVE MATERIAL
 2. 10.064mil TRACE WIDTH ROUTED AS 50 OHM IMPEDANCE ON TOP LAYER AND BOTTOM LAYER.
 PLEASE REFER THE STACKUP FILE. (STACKUP FILE NAME: TEXAS_4L_50_90_100)



Symbol	Count	Hole Size	Plated	Hole Type
□	2	40.00mil (1.016mm)	NPTH	Round
☆	2	173.23mil (4.400mm)	NPTH	Round
✱	4	7.87mil (0.200mm)	PTH	Round
▽	4	125.00mil (3.175mm)	PTH	Round
○	52	12.00mil (0.305mm)	PTH	Round
⊗	70	6.00mil (0.152mm)	PTH	Round
	134	Total		

Drill Table
 FOR 6MIL DRILL +0/-6MIL
 FOR 7.874MIL DRILL +0/-7.874MIL
 FOR 12MIL DRILL +0/-12MIL
 FOR PTH DRILL +/-3MIL
 FOR NPTH DRILL +/-2MIL

DESIGN INFORMATION	
BOARD SIZE (REFER ALSO ARRAY/PANEL PROFILING INFORMATION) 54.61MM X 40.64MM	
Number of Layers :	4
MIN. TRACK WIDTH:	8 MIL
MIN. CLEARANCE:	4.706MIL
MIN. VIA DRILL SIZE:	6 MIL
MINIMUM ANNULAR RING 4 MIL EXTERNAL PER IPC-D-275 CLASS 2 LEVEL C REGISTRATION TOLERANCES: METAL +/- 5 MIL, HOLES +/- 3 MIL	
MATERIAL:	
<input type="checkbox"/> FR-408 <input checked="" type="checkbox"/> FR-4 High Tg <input type="checkbox"/> OTHER _____	
THICKNESS:	<input checked="" type="checkbox"/> 63 MIL (1.6mm) +/-10% <input type="checkbox"/> OTHER _____
TOLERANCE:	<input checked="" type="checkbox"/> ANSI IPC-6012 TYPE 3 CLASS 2 <input type="checkbox"/> OTHER +/- _____
BOW & TWIST:	<input checked="" type="checkbox"/> ANSI IPC-6012 TYPE 3 CLASS 2 <input type="checkbox"/> OTHER +/- _____
COPPER THICKNESS (FINISHED):	
OUTER:	<input checked="" type="checkbox"/> 1.4MIL (1oz) <input type="checkbox"/> 2MIL (1.4oz) <input type="checkbox"/> 2.8MIL (2oz)
INNER SIGNAL:	<input checked="" type="checkbox"/> 1.4MIL (1oz) <input type="checkbox"/> 2.8MIL (2oz) <input type="checkbox"/> N/A
DRILLING:	
REFERENCE:	<input checked="" type="checkbox"/> AS SHOWN <input checked="" type="checkbox"/> NC_DRILL FILES
PTH MIN COPPER THICKNESS:	<input checked="" type="checkbox"/> 1MIL <input type="checkbox"/> OTHER _____
BOARD FINISH:	
SILKSCREEN:	<input checked="" type="checkbox"/> TOP <input type="checkbox"/> BOTTOM
SILKSCREEN COLOR:	<input checked="" type="checkbox"/> WHITE <input type="checkbox"/> OTHER _____
SOLDER RESIST COLOR:	<input checked="" type="checkbox"/> GREEN <input type="checkbox"/> BLUE <input type="checkbox"/> OTHER _____
SURFACE FINISH:	
<input checked="" type="checkbox"/> IMMERSION GOLD (ENIG) <input type="checkbox"/> ENEPIG <input type="checkbox"/> IMM. TIN/SILVER OR EQUIV <input type="checkbox"/> OTHER _____	
ARRAY/PANEL:	
<input type="checkbox"/> CUT AND TRIM PER MECH LAYER 1 <input type="checkbox"/> N.C. ROUTE <input type="checkbox"/> V. SCORE	
CERTIFICATION: MATERIALS AND WORKMANSHIP FOR ALL PCBs TO MEET OR EXCEED THE REQUIREMENTS OF:	
<input checked="" type="checkbox"/> ANSI IPC-A-600F CLASS -> <input type="checkbox"/> 1 <input checked="" type="checkbox"/> 2 <input type="checkbox"/> 3	
<input checked="" type="checkbox"/> UL 94V-0 <input checked="" type="checkbox"/> RoHS <input type="checkbox"/> OTHER PER ORDER	
ADDITIONAL REQUIREMENTS: VIA TENTING: YES <input type="checkbox"/> NO <input checked="" type="checkbox"/>	
MICROSECTION: <input type="checkbox"/> YES IMPEDANCE CONTROL: YES <input checked="" type="checkbox"/> NO <input type="checkbox"/>	
BARE BOARD ELEC. TEST: <input type="checkbox"/> NONE <input checked="" type="checkbox"/> REQUIRED <input type="checkbox"/> PER ORDER	
MANUFACTURER'S UL: <input type="checkbox"/> RAIL <input type="checkbox"/> METAL <input checked="" type="checkbox"/> SILK	



PROJECT TITLE:
73dB SNR, 7.5MSPS, 14-bit Analog Front-end Using Time-Interleaved SAR ADCs

DESIGNED FOR:
Public Release

FILE NAME:
TIDA-01355_E1_PCB.PcbDoc

ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: XX####	REV: E1	SUN REV: Not In VersionControl	Texas Instruments (TI) and/or its licensors do not warrant the accuracy or completeness of this specification or any information contained therein. TI and/or its licensors do not warrant that this design will meet the specifications, will be suitable for your application or fit for any particular purpose, or will operate in an implementation. TI and/or its licensors do not warrant that the design is production worthy. You should completely validate and test your design implementation to confirm the system functionality for your application.	ENGINEER: Sharad Yadav	LAYOUT BY: Sharad Yadav
LAYER NAME = Drill Drawing	TID #: TIDA-01355	GENERATED : 5/15/2017 7:23:06 PM	TEXAS INSTRUMENTS		SCALE: 1.00	ALTIM DESIGNER VERSION: 16.1.12.290
PLOT NAME =Fabrication Drawing						

IMPORTANT NOTICE FOR TI DESIGN INFORMATION AND RESOURCES

Texas Instruments Incorporated ("TI") technical, application or other design advice, services or information, including, but not limited to, reference designs and materials relating to evaluation modules, (collectively, "TI Resources") are intended to assist designers who are developing applications that incorporate TI products; by downloading, accessing or using any particular TI Resource in any way, you (individually or, if you are acting on behalf of a company, your company) agree to use it solely for this purpose and subject to the terms of this Notice.

TI's provision of TI Resources does not expand or otherwise alter TI's applicable published warranties or warranty disclaimers for TI products, and no additional obligations or liabilities arise from TI providing such TI Resources. TI reserves the right to make corrections, enhancements, improvements and other changes to its TI Resources.

You understand and agree that you remain responsible for using your independent analysis, evaluation and judgment in designing your applications and that you have full and exclusive responsibility to assure the safety of your applications and compliance of your applications (and of all TI products used in or for your applications) with all applicable regulations, laws and other applicable requirements. You represent that, with respect to your applications, you have all the necessary expertise to create and implement safeguards that (1) anticipate dangerous consequences of failures, (2) monitor failures and their consequences, and (3) lessen the likelihood of failures that might cause harm and take appropriate actions. You agree that prior to using or distributing any applications that include TI products, you will thoroughly test such applications and the functionality of such TI products as used in such applications. TI has not conducted any testing other than that specifically described in the published documentation for a particular TI Resource.

You are authorized to use, copy and modify any individual TI Resource only in connection with the development of applications that include the TI product(s) identified in such TI Resource. NO OTHER LICENSE, EXPRESS OR IMPLIED, BY ESTOPPEL OR OTHERWISE TO ANY OTHER TI INTELLECTUAL PROPERTY RIGHT, AND NO LICENSE TO ANY TECHNOLOGY OR INTELLECTUAL PROPERTY RIGHT OF TI OR ANY THIRD PARTY IS GRANTED HEREIN, including but not limited to any patent right, copyright, mask work right, or other intellectual property right relating to any combination, machine, or process in which TI products or services are used. Information regarding or referencing third-party products or services does not constitute a license to use such products or services, or a warranty or endorsement thereof. Use of TI Resources may require a license from a third party under the patents or other intellectual property of the third party, or a license from TI under the patents or other intellectual property of TI.

TI RESOURCES ARE PROVIDED "AS IS" AND WITH ALL FAULTS. TI DISCLAIMS ALL OTHER WARRANTIES OR REPRESENTATIONS, EXPRESS OR IMPLIED, REGARDING TI RESOURCES OR USE THEREOF, INCLUDING BUT NOT LIMITED TO ACCURACY OR COMPLETENESS, TITLE, ANY EPIDEMIC FAILURE WARRANTY AND ANY IMPLIED WARRANTIES OF MERCHANTABILITY, FITNESS FOR A PARTICULAR PURPOSE, AND NON-INFRINGEMENT OF ANY THIRD PARTY INTELLECTUAL PROPERTY RIGHTS.

TI SHALL NOT BE LIABLE FOR AND SHALL NOT DEFEND OR INDEMNIFY YOU AGAINST ANY CLAIM, INCLUDING BUT NOT LIMITED TO ANY INFRINGEMENT CLAIM THAT RELATES TO OR IS BASED ON ANY COMBINATION OF PRODUCTS EVEN IF DESCRIBED IN TI RESOURCES OR OTHERWISE. IN NO EVENT SHALL TI BE LIABLE FOR ANY ACTUAL, DIRECT, SPECIAL, COLLATERAL, INDIRECT, PUNITIVE, INCIDENTAL, CONSEQUENTIAL OR EXEMPLARY DAMAGES IN CONNECTION WITH OR ARISING OUT OF TI RESOURCES OR USE THEREOF, AND REGARDLESS OF WHETHER TI HAS BEEN ADVISED OF THE POSSIBILITY OF SUCH DAMAGES.

You agree to fully indemnify TI and its representatives against any damages, costs, losses, and/or liabilities arising out of your non-compliance with the terms and provisions of this Notice.

This Notice applies to TI Resources. Additional terms apply to the use and purchase of certain types of materials, TI products and services. These include; without limitation, TI's standard terms for semiconductor products (<http://www.ti.com/sc/docs/stdterms.htm>), [evaluation modules](#), and [samples](http://www.ti.com/sc/docs/sampterm.htm) (<http://www.ti.com/sc/docs/sampterm.htm>).

Mailing Address: Texas Instruments, Post Office Box 655303, Dallas, Texas 75265
Copyright © 2017, Texas Instruments Incorporated